# Reliability Test Report

Product Name: CA-IS3050WG

Report Version: V1.0

| Prepared by | Reviewed by | Approved by |
| --- | --- | --- |
| 胡静洁 | 唐申 | 陈亮 |

# Contents

# 1. Overview

Reliability testing of microelectronic products is a risk mitigation process designed to ensure the service life of device in customer applications. Semiconductor wafer manufacturing process and package-level reliability can be assessed in a variety of ways and may include accelerated environmental test conditions. Chipanalog evaluates manufacturability of the device to verify a robust silicon and assembly flow to ensure continuity of supply to customers. Chipanalog qualifies new devices, significant changes, and product families based on JEDEC JESD47.

# 2. Part Number List

| **Package Type** | **Part Number** |
|---|---|
| SOIC8-WWB(WG) | CA-IS3050WG |

Note: JEDEC specification is designed to also qualify a family of similar components utilizing the same fabrication process, design rules, and similar circuits. The family qualification may also be applied to a package family where the construction is the same and only the size and number of leads differs.

# 3. Product Information

## 3.1. Wafer Information

| | | |
|---|---|---|
| **Wafer** | QINGLONG | SATURN |
| **Fab Process** | 18BCD | 18BCD |

## 3.2. Package Information

| | |
|---|---|
| **Assembly site** | JCET |
| **FT site** | JCET |
| **Package** | SOIC8-WWB |
| **Lead frame** | Cu |
| **Bond wire** | 20um AuPdCu |
| **MSL level** | MSL3 |

# 4. Reliability Qualification Plan

## 4.1. Device Qualification Test Requirements

| Stress | Ref. | Abbv. | Conditions | Duration /Accept |
|---|---|---|---|---|
| Electrical Parameter Assessment | JESD86 | ED | Per Datasheet | Per Datasheet |
| High Temperature Operating Life | JESD22-A108, JESD85 | HTOL | $T_J \geq 125°C$<br>$V_{CC} \geq V_{CC}$ max | 1000 hrs/0 Fail |
| Human Body Model ESD | JS-001 | ESD-HBM | $T_A = 25°C$ | Classification |
| Charged Device Model ESD | JS-002 | ESD-CDM | $T_A = 25°C$ | Classification |
| Latch-Up | JESD78 | LU | Class I or Class II | Classification |

## 4.2. Nonhermetic Package Qualification Test Requirements

| Stress | Ref. | Abbv. | Conditions | Duration /Accept |
|---|---|---|---|---|
| MSL Preconditioning | JESD22-A113 | PC | Per appropriate MSL level per J-STD-020 | Electrical Test (optional) |
| High Temperature Storage | JESD22-A103 & A113 | HTSL | 150°C, 1000 hrs | 1000 hrs/0 Fail |
| Temperature Humidity Bias | JESD22-A101 | THB | 85°C, 85% RH, $V_{CC}$ max | 1000 hrs/0 Fail |
| Highly Accelerated Temperature and Humidity Stress | JESD22-A110 | HAST | 130°C/110°C, 85% RH, 33.3/17.7 psia, $V_{cc1}$= 5.5V, $V_{cc2}$= 5.5V | 96/264 hrs/0 Fail |
| Temperature Cycling | JESD22-A104 | TC | -65°C to 150°C | 500 cycles/0 Fail |
| Unbiased Temperature/Humidity | JESD22-A102 | AC | 121°C, 100% RH, 29.7psia | 96 hrs/0 Fail |
| Unbiased Temperature/Humidity | JESD22-A118 | UHAST | 130°C/110°C, 85% RH, 33.3/17.7 psia | 96/264 hrs/0 Fail |
| Bond Pull Strength | JESD22-B120 | BPS | Characterization, Pre Encapsulation | Ppk≥1.66 or Cpk≥1.33 |
| Bond Shear | JESD22-B116 | BS | Characterization, Pre Encapsulation | Ppk≥1.66 or Cpk≥1.33 |
| Solderability | M2003 JESD22-B102 | SD | Characterization | 95% coverage |

Note: Either HAST or THB may be chosen. If THB or HAST is run, then UHAST need not be run. Autoclave is not recommended as a qualification test; Unbiased or biased HAST is the recommended stress and is required for organic substrates instead of Autoclave.

# 5. Reliability Test Results

## 5.1. Device Reliability Test Results

| Stress | Condition | Duration | Sample Size | Result | Classification |
|---|---|---|---|---|---|
| ED | Per Datasheet | / | 10*3 lot | Pass | / |
| HTOL | TA = 125°C, $V_{cc1}$= 5.5V, $V_{cc2}$= 5.5V | 1000 hrs | 77*3 lot | Pass | / |
| ESD-HBM | $T_A$ = 25°C | / | 3*1 lot | Pass | Class 3A |
| ESD-CDM | $T_A$ = 25°C | / | 3*1 lot | Pass | Class C3 |
| LU | $T_A$ = 25°C | / | 3*1 lot | Pass | Class I.A |

Note: HTOL test data refers to qualification of the same product family.

## 5.2. Package Reliability Test Results

| Package Type: SOIC8-WWB | | | | |
|---|---|---|---|---|
| **Stress** | **Condition** | **Duration** | **Sample size** | **Results** |
| PC | MSL 3 | / | 231*3 lot | Pass |
| HTSL | $T_A$ = 150°C | 1000 hrs | 77*3 lot | Pass |
| HAST | 130°C, 85% RH, 33.3psia, $V_{cc1}$= 5.5V, $V_{cc2}$= 5.5V | 96 hrs | 77*3 lot | Pass |
| TC | -65°C to 150°C | 0~500 cycles | 77*3 lot | Pass |
| UHAST | 130°C, 85% RH, 33.3psia | 96 hrs | 77*3 lot | Pass |
| BPS | JESD22-B120 | / | 30 bonds/5 ea. | Pass |
| BS | JESD22-B116 | / | 30 bonds/5 ea. | Pass |
| SD | Steam aging, 245°C dipping | 5s | 22 leads*3 lot | Pass |

Note: 1 lot package reliability test data comes from qualification of CA-IS3050WG, another 2 lot package reliability data refer to generic data of same package family.

# 6. Conclusion

CA-IS3050WG is qualified according to JEDEC standards.

## Disclaimer

This information is provided to assist customers in design and development. It could change for technology innovation without notice.

The devices are shipped after passing final test. Customers are responsible to conduct sufficient engineering and additional qualification testing to determine whether a device is suitable for use in their applications.

License to customers to use the information is limited to the development of applications using the device. Apart from above, the information shall not be reproduced or displayed, and Chipanalog shall not be liable for any claims, compensation, costs, losses or liabilities arising out of the use of the information.

## Trademarks

Chipanalog Inc.®、Chipanalog® are trademarks of Chipanalog.

## Revision History

| Revision | Change Log | Date |
|---|---|---|
| V1.0 | Initial release | Oct, 2024 |